

Polymer PTC Devices *Surface mount fuses*

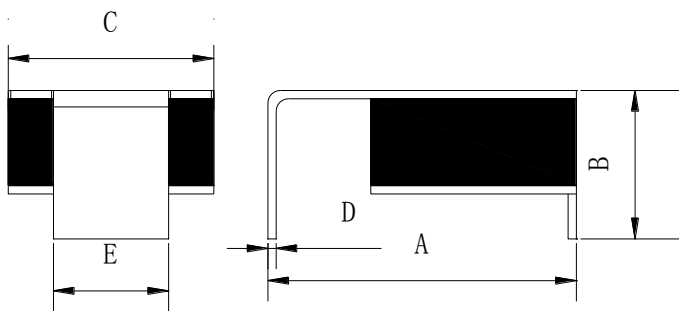
Features

- Surface mount devices
- Withstanding high interrupt voltage
- Agency Recognition: UL
- Lead-free and compliant with the European Union RoHS Directive (EU)2015/863



Product Dimensions (mm)

Part number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
DW080AF	6.7	7.9	2.7	3.7	4.8	5.3	0.2	0.4	2.5	3.1



Electrical Characteristics

Part number	I_H	I_T	T_{trip}		$V_{max\ interrupt}$	I_{max}	$P_{d\ typ}$	R_{min}	R_{max}	R_{1max}
	(A)	(A)	Current(A)	Time(S)	(V)	(A)	(W)	(Ω)	(Ω)	(Ω)
DW080AF	0.080	0.160	1.00	0.80	250	3.0	1.00	14.0	22.0	40.0

I_H =Hold current: maximum current at which the device will not trip at 25°C still air.

I_T =Trip current: minimum current at which the device will always trip at 25°C still air.

T_{trip} =Typical time to trip(s) at assigned current.

$V_{max\ interrupt}$ =Maximum interrupt voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

$P_{d\ typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25°C prior to tripping.

R_{max} =Maximum device resistance at 25°C prior to tripping.

R_{1max} =Maximum device resistance at 25°C one hour post trip.

Thermal Derating Chart-IH(A)

Part number	Maximum ambient operating temperatures(°C)									
	-40	-20	0	25	40	50	60	70	85	
DW080AF	0.124	0.110	0.095	0.080	0.066	0.059	0.051	0.044	0.033	

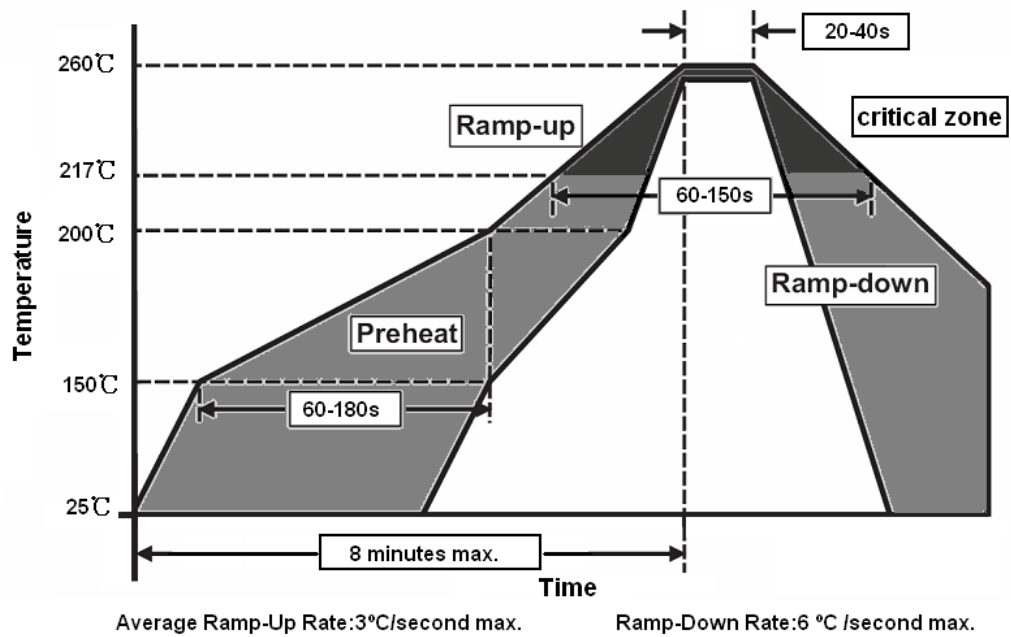
Package Information

Bulk: 1000pcs per bag.

Tape & Reel: 2000pcs per reel.



Solder Reflow Recommendations



* Recommended reflow methods: IR, Vapor phase, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.